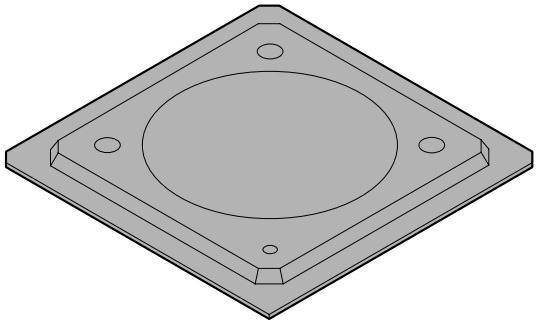
PLASTIC BALL GRID ARRAY PACKAGE
543 PIN PLASTIC

BGA-543P-M01

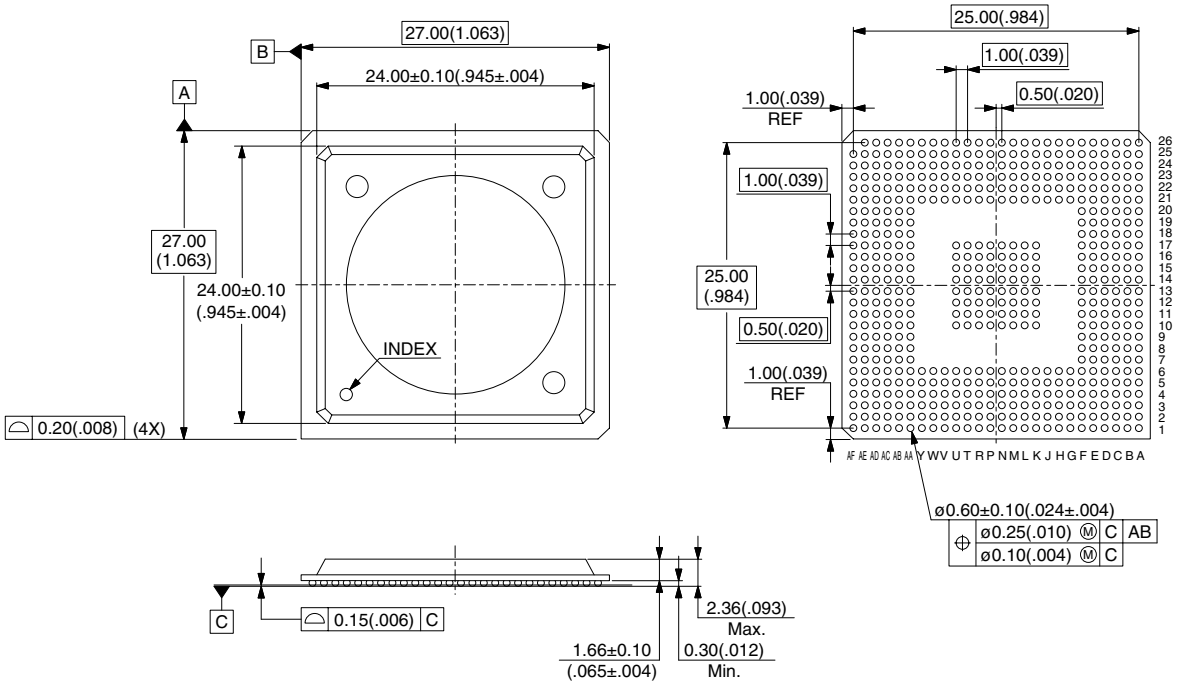
543-pin plastic TEBGA



(BGA-543P-M01)

Lead pitch	1.00 mm
Package width × package length	27.00 mm × 27.00 mm
Lead shape	Ball
Sealing method	Plastic mold
Mounting height	2.36 mm MAX
Weight	2.60 g

543-pin plastic TEBGA
(BGA-543P-M01)



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Dimensions in mm (inches).
Note: The values in parentheses are reference values.

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